

TIDA-01347 Test Results

About Test Results

This reference design incorporates the DLP 0.66" 4K UHD chipset which includes the DLP660TE DMD, the DLPC4422 controller, and the DLPA100 power supply and motor driver. The TI design enables faster development cycles for this specific chipset.

If You Need Assistance

Refer to the DLP and MEMS TI E2E Community support forums:

https://e2e.ti.com/support/dlp_mems_micro-electro-mechanical_systems/video_and_data_display/f/947

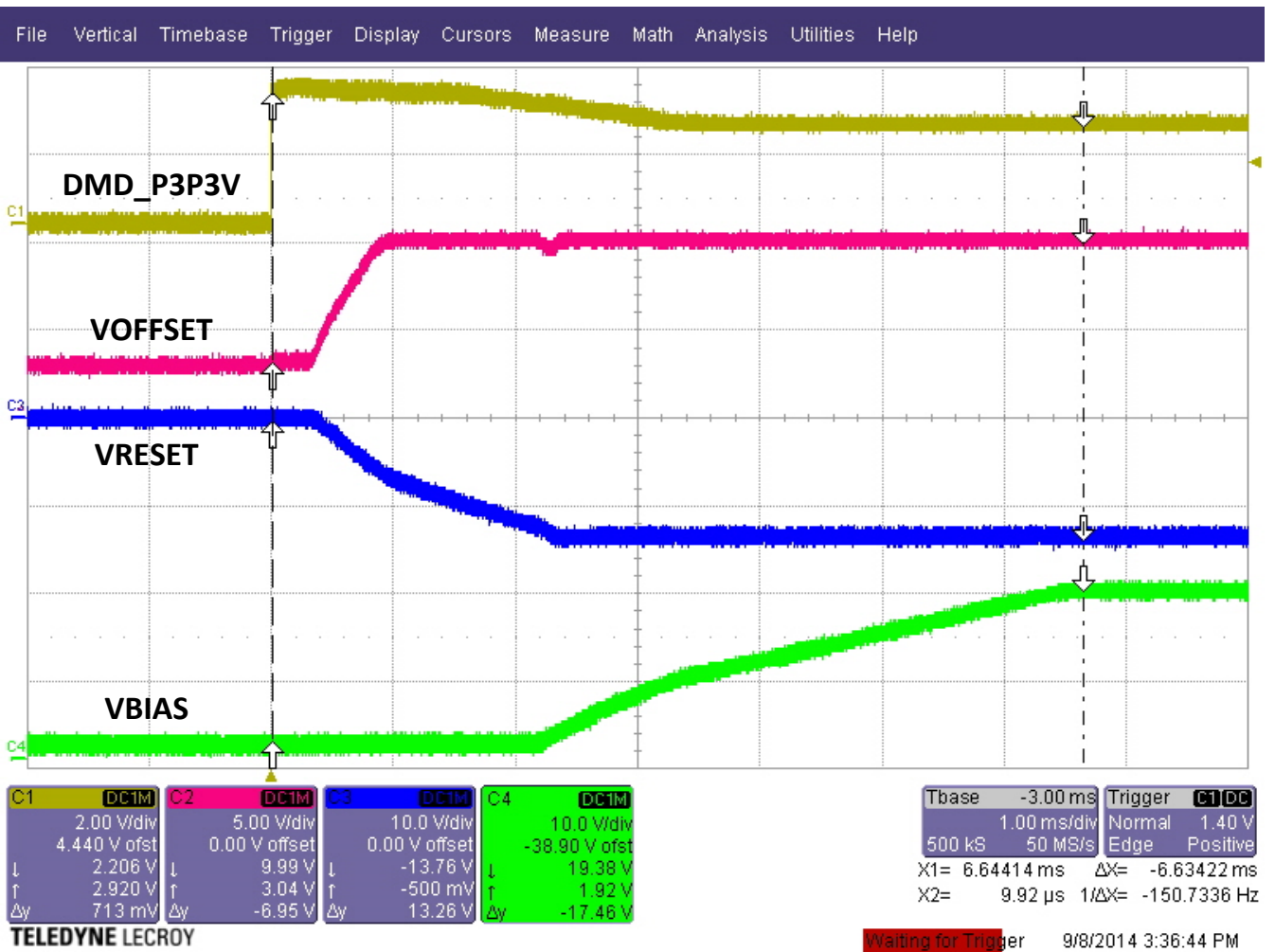
EMI Compliance

The TIDA-01347 reference design hardware was not optimized or tested for low EMI performance. Users of the information found in this TI design are responsible for ensuring their products meet all applicable EMI regulations.

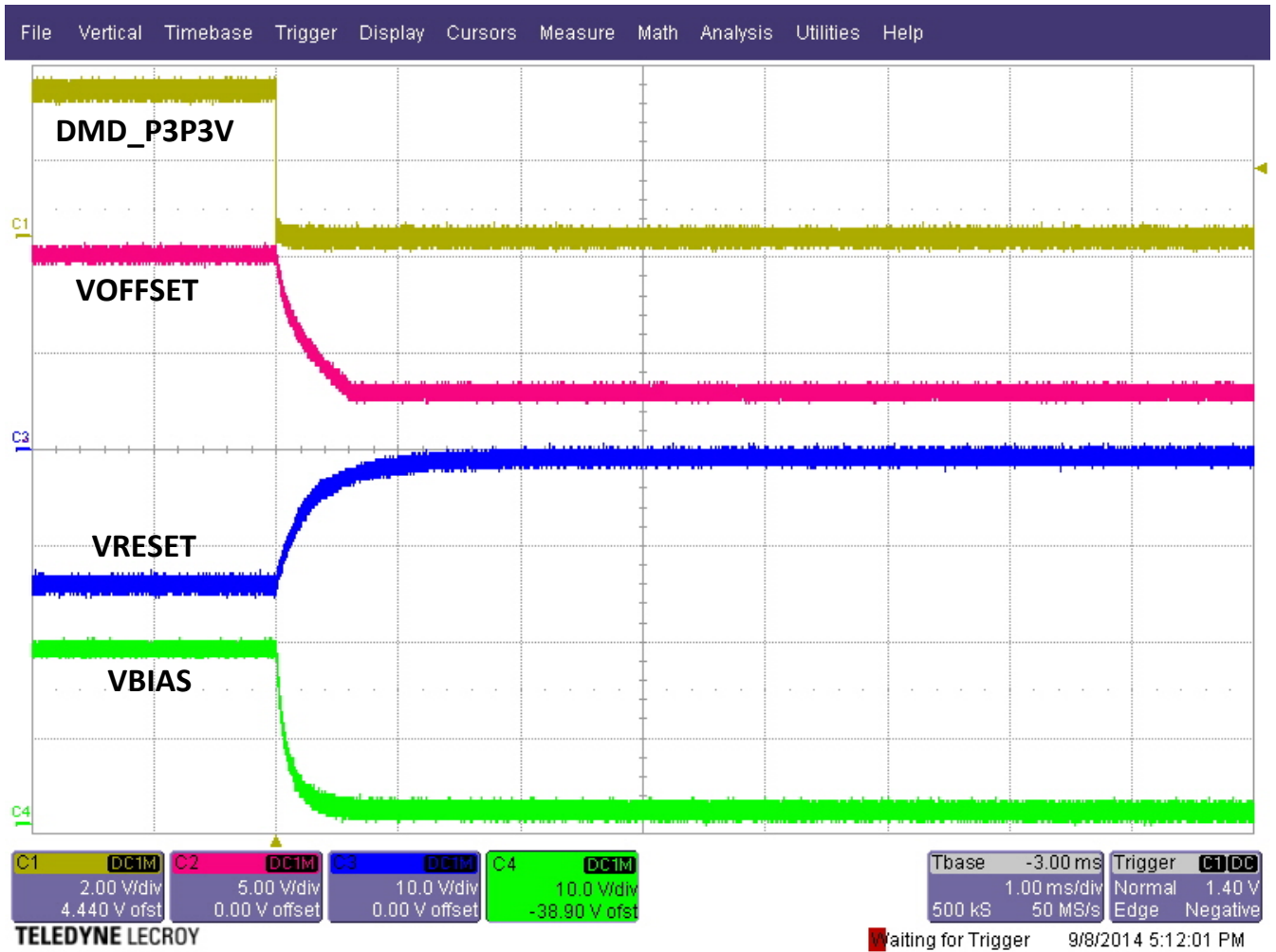
Power Up and Power Down Timing Measurements

Power Up and Power Down timing requirements are described in detail in the DLP660TE datasheet. Key signals measured are power supplies to the DMD: DMD_P3P3V, VBIAS, VOFFSET, and VRESET. For more details on the timing requirements please refer to the DLP660TE device datasheet.

Power Up Timing Measurements



Power Down Timing Measurements



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